

WLP

Wafer Chip Size Package



WLP uses interconnection technology to effectively utilize the chip area by making it possible to form electrodes over the entire chip surface. This eliminates the need for the wire bonding space required by previous wiring methods. Also, electrodes are formed using copper posts for a simple structure.

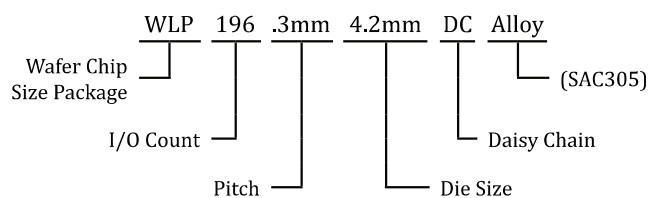
All of this means that the area of the finished package is exactly the same compact size as the original chip. It also simplifies mounting and contributes to easier high-density mounting. WLP is the perfect choice for packaging chips used in portable telephones, digital cameras, and other applications where mounting space is severely restricted.

Part Description	I/O Count	Pitch	Body Size	Matrix	Alloy
.3mm Pitch					
WLP100-.3mm-3mm-DC	100	.3mm	3mm	10x10	96.5%Sn/3.0%Ag/0.5%Cu
WLP144-.3mm-3.6mm-DC	144	.3mm	3.6mm	12x12	96.5%Sn/3.0%Ag/0.5%Cu
WLP196-.3mm-4.2mm-DC	196	.3mm	4.2mm	14x14	96.5%Sn/3.0%Ag/0.5%Cu
WLP256-.3mm-4.8mm-DC	256	.3mm	4.8mm	16x16	96.5%Sn/3.0%Ag/0.5%Cu
WLP264-.3mm-6mm-DC	264	.3mm	6mm	17x17	96.5%Sn/3.0%Ag/0.5%Cu
WLP400-.3mm-6mm-DC	400	.3mm	6mm	20x20	96.5%Sn/3.0%Ag/0.5%Cu
WLP676-.3mm-7.8mm-DC	676	.3mm	7.8mm	26x26	96.5%Sn/3.0%Ag/0.5%Cu
WLP900-.3mm-9mm-DC	900	.3mm	9mm	30x30	96.5%Sn/3.0%Ag/0.5%Cu
WLP1600-.3mm-12mm-DC	1600	.3mm	12mm	40x40	96.5%Sn/3.0%Ag/0.5%Cu
.4mm Pitch					
WLP100-.4mm-4mm-DC	100	.4mm	4mm	10x10	96.5%Sn/3.0%Ag/0.5%Cu
WLP144-.4mm-4.8mm-DC	144	.4mm	4.8mm	12x12	96.5%Sn/3.0%Ag/0.5%Cu
WLP144-.4mm-6mm-DC	144	.4mm	6mm	13x13/4-Row	96.5%Sn/3.0%Ag/0.5%Cu
WLP196-.4mm-5.6mm-DC	196	.4mm	5.6mm	14x14	96.5%Sn/3.0%Ag/0.5%Cu
WLP256-.4mm-6.4mm-DC	256	.4mm	6.4mm	16x16	96.5%Sn/3.0%Ag/0.5%Cu
WLP400-.4mm-8mm-DC	400	.4mm	8mm	20x20	96.5%Sn/3.0%Ag/0.5%Cu
WLP676-.4mm-10.4mm-DC	676	.4mm	10.4mm	26x26	96.5%Sn/3.0%Ag/0.5%Cu
WLP900-.4mm-12mm-DC	900	.4mm	12mm	30x30	96.5%Sn/3.0%Ag/0.5%Cu
.5mm Pitch					
WLP100-.5mm-5mm-DC	100	.5mm	5mm	10x10	96.5%Sn/3.0%Ag/0.5%Cu
WLP144-.5mm-6mm-DC	144	.5mm	6mm	12x12	96.5%Sn/3.0%Ag/0.5%Cu
WLP196-.5mm-7mm-DC	196	.5mm	7mm	14x14	96.5%Sn/3.0%Ag/0.5%Cu
WLP256-.5mm-8mm-DC	256	.5mm	8mm	16x16	96.5%Sn/3.0%Ag/0.5%Cu
WLP400-.5mm-10mm-DC	400	.5mm	10mm	20x20	96.5%Sn/3.0%Ag/0.5%Cu
WLP676-.5mm-13mm-DC	676	.5mm	13mm	26x26	96.5%Sn/3.0%Ag/0.5%Cu
WLP900-.5mm-15mm-DC	900	.5mm	15mm	30x30	96.5%Sn/3.0%Ag/0.5%Cu

Notes

- Ultra thin type, Ultra miniature, Lightweight
- High current capacity and good heat radiation
- Stress buffer structure
- High reliability of WLP as semiconductor package makes KGD issues cleared.
- Cu-to-Cu wiring structure
- Include inductors of high Q value
- Possibility of SMT assembly
- Coplanarity (5 to 10 μ m)
- Available diced and left in ring or in trays.

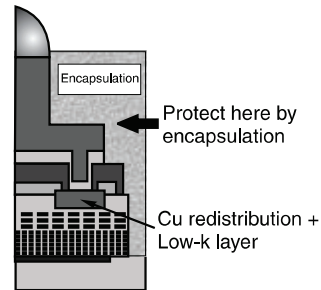
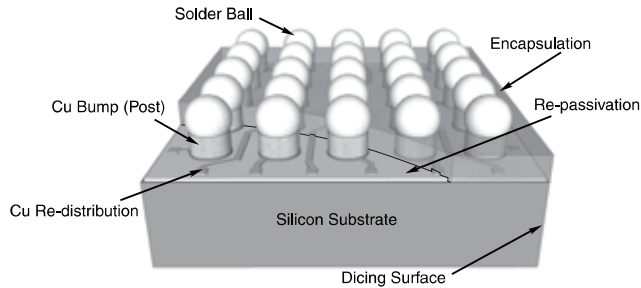
Part Description System



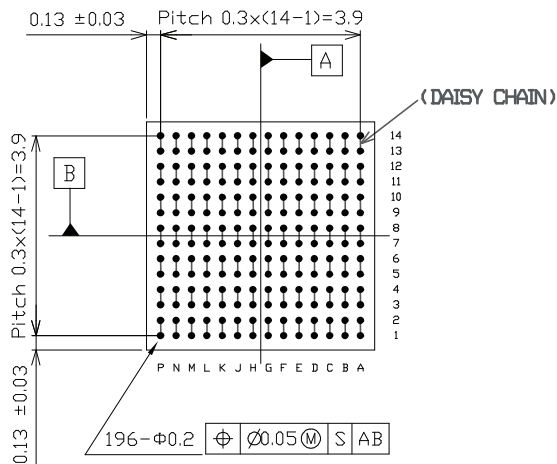
- Add "TR" to end of part number for die on Tape and Reel.
- Add "SAC305" to end of part number for Lead-Free.

WLP

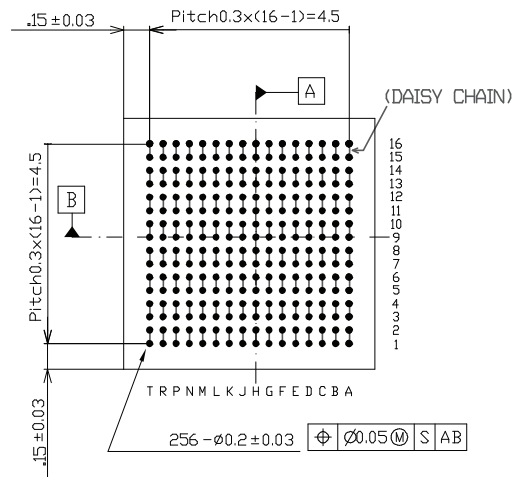
Wafer Chip Size Package



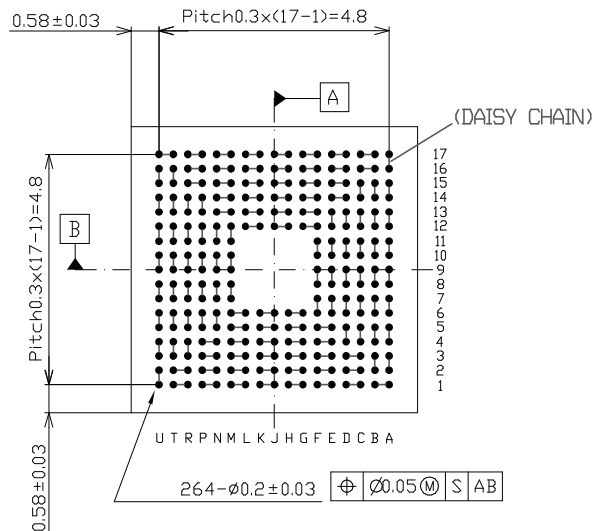
WLP196-.3mm-4.2mm (14x14 Matrix)



WLP256-.3mm-4.8mm (16x16 Matrix)



WLP264-.3mm-6mm (17x17 Matrix)



WLP400-.3mm-6mm (20x20 Matrix)

